



Material Content Data Sheet



Sales Product Name		ICE3B1565J		Issued		29. August 2013		
MA#		MA001068592						
Package		PG-DIP-8-9		Weight*		518.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.255	0.63	0.63	6280	6280
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		103	
	non noble metal	zinc	7440-66-6	0.213	0.04		412	
	non noble metal	iron	7439-89-6	4.266	0.82		8231	
wire	non noble metal	copper	7440-50-8	173.237	33.42	34.29	334192	342938
	noble metal	gold	7440-57-5	0.422	0.08	0.08	814	814
	encapsulation	organic material	carbon black	1333-86-4	1.308	0.25		2523
encapsulation	plastics	epoxy resin	-	37.925	7.32		73161	
	inorganic material	silicondioxide	60676-86-0	287.705	55.50	63.07	555013	630697
leadfinish	non noble metal	tin	7440-31-5	7.496	1.45	1.45	14460	14460
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1545	1545
glue	plastics	epoxy resin	-	0.254	0.05		490	
	noble metal	silver	7440-22-4	1.439	0.28	0.33	2776	3266
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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